

Base Material: FR4 Er=4.2

Overall Thickness: 1.60 mm (±10%)

Final contour of the BOARD

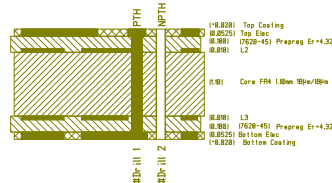
Y: BOARD

BOARD SIZE: 188.88 x 193.88

PCB Diagram

**LAYER STACK-UP 4**  
Layer pairs & Via appearance  
Overall board thickness 1.60 mm (±10%)

Diff Coated Coplanar Waveguide With Ground  
( 90 Ohm impedance ) unit:mm  
0.28 0.22 0.28 0.22 0.28  
(0.828) Top Coating  
(0.828) Top Elec  
(0.828) Prepreg Er=4.32  
(0.828) L2  
(0.828) L3  
(0.828) (0.828-45) Prepreg Er=4.32  
(0.828) Bottom Elec  
(0.828) Bottom Coating  
(0.828) Core FR4 1.60mm Wp/Wm  
#Drill 1  
#Drill 2



Final coating  
**LEAD FREE**

LAYER NAME	GERBER FILE
X TOP PLACEMENT	31TPL.apl
X TOP PASTE	25TP5.apl
X TOP SILK SCREEN	23TS5.apl
X TOP SOLDER RESIST	21TSR.apl
X TOP ELEC (Top Elec)	02TE.apl
X INNERIL21	03INNER1.apl
X INNERIL23	08INNER2.apl
X BOTTOM ELEC(Bottom Elec)	09BE.apl
X BOTTOM SOLDER RESIST	22BSR.apl
X BOTTOM SILK SCREEN	24BS5.apl
X BOTTOM PLACEMENT	32BPL.apl

#Drill 1 TOP to BOT /plated holes/			#Drill 2 TOP to BOT /non plated holes/		
#	Size(mm)	Let/Count	#	Size(mm)	Let/Count
1	0.28	- 42	1	3.00	- 6
2	0.38	- 2473	2	-	-
3	0.68	- 74	3	-	-
4	1.00	- 4	4	-	-
5	1.10	- 6	5	-	-
6	1.20	- 12	6	-	-
7	1.70	- 10	7	-	-
8	1.80	- 4	8	-	-
9	2.10	- 4	9	-	-
10	2.50	- 2	10	-	-
11	-	-	11	-	-
12	-	-	12	-	-
13	-	-	13	-	-
14	-	-	14	-	-
Drill size after plating					

